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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, EBI/EMI, I²C, SLDM, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	93
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	PG-TQFP-128-2
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-c161jc-lf-ca

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- Idle, Sleep, and Power Down Modes with Flexible Power Management
- Programmable Watchdog Timer and Oscillator Watchdog
- Up to 93 General Purpose I/O Lines,
  partly with Selectable Input Thresholds and Hysteresis
- Supported by a Large Range of Development Tools like C-Compilers,
  Macro-Assembler Packages, Emulators, Evaluation Boards, HLL-Debuggers,
  Simulators, Logic Analyzer Disassemblers, Programming Boards
- On-Chip Bootstrap Loader
- 128-Pin TQFP Package

This document describes several derivatives of the C161 group. **Table 1** enumerates these derivatives and summarizes the differences. As this document refers to all of these derivatives, some descriptions may not apply to a specific product.

Table 1 C161CS/JC/JI Derivative Synopsis

Derivative	On-Chip Program Memory	Serial Bus Interface(s)	Maximum CPU Frequency
SAK-C161CS-32RF SAB-C161CS-32RF	256 KByte ROM	CAN1, CAN2	25 MHz
SAK-C161CS-LF SAB-C161CS-LF	---	CAN1, CAN2	25 MHz
SAK-C161JC-32RF SAB-C161JC-32RF	256 KByte ROM	CAN1, SDLM	25 MHz
SAK-C161JC-LF SAB-C161JC-LF	---	CAN1, SDLM	25 MHz
SAK-C161JI-32RF SAB-C161JI-32RF	256 KByte ROM	SDLM	25 MHz
SAK-C161JI-LF SAB-C161JI-LF	---	SDLM	25 MHz

For simplicity all versions are referred to by the term **C161CS/JC/JI** throughout this document.

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin No.	Input Outp.	Function
P4		IO	Port 4 is an 8-bit bidirectional I/O port. It is bit-wise programmable for input or output via direction bits. For a pin configured as input, the output driver is put into high-impedance state. The Port 4 outputs can be configured as push/pull or open drain drivers. The input threshold of Port 4 is selectable (TTL or special). Port 4 can be used to output the segment address lines and for serial interface lines:[1)]
P4.0	70	O	A16 Least Significant Segment Address Line
P4.1	71	O	A17 Segment Address Line
P4.2	72	O	A18 Segment Address Line
P4.3	73	O	A19 Segment Address Line
P4.4	74	O	A20 Segment Address Line,
		I	CAN2_RxD CAN 2 Receive Data Input, (**C161CS**)
		I	SDL_RxD SDLM Receive Data Input (**C161JC/JI**)
P4.5	75	O	A21 Segment Address Line,
		I	CAN1_RxD CAN 1 Receive Data Input, (**C161CS/JC**)
P4.6	76	O	A22 Segment Address Line,
		O	CAN1_TxD CAN 1 Transmit Data Output, (**C161CS/JC**)
		O	CAN2_TxD CAN 2 Transmit Data Output, (**C161CS**)
		I	SDL_RxD SDLM Receive Data Input (**C161JC/JI**)
P4.7	77	O	A23 Most Significant Segment Address Line,
		I	CAN1_RxD CAN 1 Receive Data Input, (**C161CS/JC**)
		O	CAN2_TxD CAN 2 Transmit Data Output, (**C161CS**)
		I	CAN2_RxD CAN 2 Receive Data Input, (**C161CS**)
		O	SDL_TxD SDLM Transmit Data Output (**C161JC/JI**)
$\overline{RD}$	80	O	External Memory Read Strobe. $\overline{RD}$ is activated for every external instruction or data read access.
$\overline{WR}$/ $\overline{WRL}$	81	O	External Memory Write Strobe. In $\overline{WR}$-mode this pin is activated for every external data write access. In $\overline{WRL}$-mode this pin is activated for low byte data write accesses on a 16-bit bus, and for every data write access on an 8-bit bus. See WRCFG in register SYSCON for mode selection.

Functional Description

The architecture of the C161CS/JC/JI combines advantages of both RISC and CISC processors and of advanced peripheral subsystems in a very well-balanced way. In addition the on-chip memory blocks allow the design of compact systems with maximum performance.
The following block diagram gives an overview of the different on-chip components and of the advanced, high bandwidth internal bus structure of the C161CS/JC/JI.

Note: All time specifications refer to a CPU clock of 25 MHz (see definition in the AC Characteristics section).

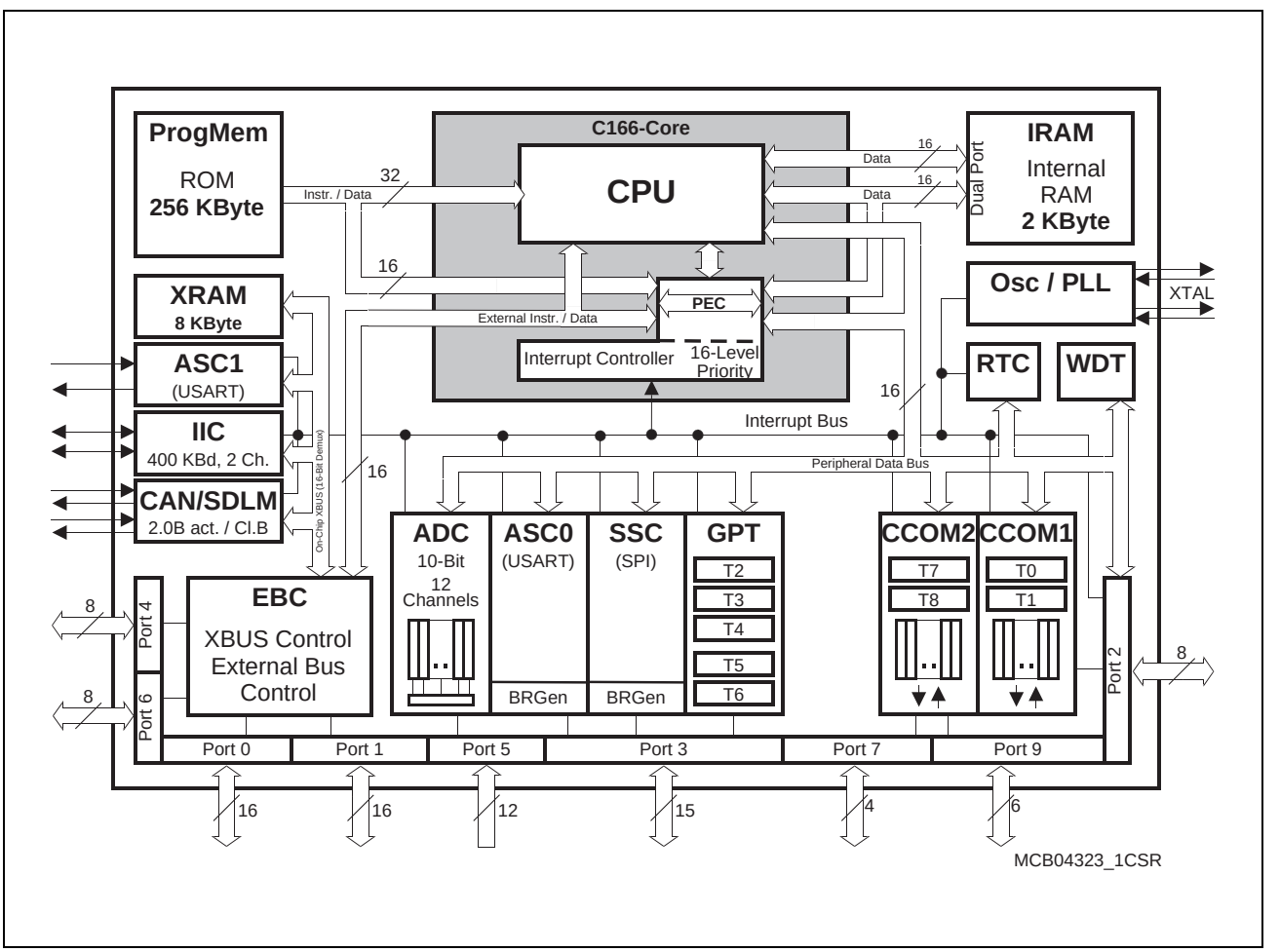


Figure 3 Block Diagram

The program memory, the internal RAM (IRAM) and the set of generic peripherals are connected to the CPU via separate buses. A fourth bus, the XBUS, connects external resources as well as additional on-chip resoures, the X-Peripherals (see **Figure 3**).

The XBUS resources (XRAM, CAN, SDLM, IIC, ASC1) of the C161CS/JC/JI can be enabled during initialization by setting the general X-Peripheral enable bit XPEN (SYSCON.2).
If the X-Peripherals remain disabled they consume neither address space nor port pins.

Table 3 C161CS/JC/JI Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Request Flag	Enable Flag	Interrupt Vector	Vector Location	Trap Number
CAPCOM Register 30	CC30IR	CC30IE	CC30INT	$00'0114_H$	45_H
CAPCOM Register 31	CC31IR	CC31IE	CC31INT	$00'0118_H$	46_H
CAPCOM Timer 0	T0IR	T0IE	T0INT	$00'0080_H$	20_H
CAPCOM Timer 1	T1IR	T1IE	T1INT	$00'0084_H$	21_H
CAPCOM Timer 7	T7IR	T7IE	T7INT	$00'00F4_H$	$3D_H$
CAPCOM Timer 8	T8IR	T8IE	T8INT	$00'00F8_H$	$3E_H$
GPT1 Timer 2	T2IR	T2IE	T2INT	$00'0088_H$	22_H
GPT1 Timer 3	T3IR	T3IE	T3INT	$00'008C_H$	23_H
GPT1 Timer 4	T4IR	T4IE	T4INT	$00'0090_H$	24_H
GPT2 Timer 5	T5IR	T5IE	T5INT	$00'0094_H$	25_H
GPT2 Timer 6	T6IR	T6IE	T6INT	$00'0098_H$	26_H
GPT2 CAPREL Reg.	CRIR	CRIE	CRINT	$00'009C_H$	27_H
A/D Conversion Compl.	ADCIR	ADCIE	ADCINT	$00'00A0_H$	28_H
A/D Overrun Error	ADEIR	ADEIE	ADEINT	$00'00A4_H$	29_H
ASC0 Transmit	S0TIR	S0TIE	S0TINT	$00'00A8_H$	$2A_H$
ASC0 Transmit Buffer	S0TBIR	S0TBIE	S0TBINT	$00'011C_H$	47_H
ASC0 Receive	S0RIR	S0RIE	S0RINT	$00'00AC_H$	$2B_H$
ASC0 Error	S0EIR	S0EIE	S0EINT	$00'00B0_H$	$2C_H$
SSC Transmit	SCTIR	SCTIE	SCTINT	$00'00B4_H$	$2D_H$
SSC Receive	SCRIR	SCRIE	SCRINT	$00'00B8_H$	$2E_H$
SSC Error	SCEIR	SCEIE	SCEINT	$00'00BC_H$	$2F_H$
IIC Data Transfer Event	XP0IR	XP0IE	XP0INT	$00'0100_H$	40_H
IIC Protocol Event	XP1IR	XP1IE	XP1INT	$00'0104_H$	41_H
CAN1 (**C161CS/JC**)	XP2IR	XP2IE	XP2INT	$00'0108_H$	42_H
PLL/OWD and RTC	XP3IR	XP3IE	XP3INT	$00'010C_H$	43_H
ASC1 Transmit	XP4IR	XP4IE	XP4INT	$00'0120_H$	48_H
ASC1 Receive	XP5IR	XP5IE	XP5INT	$00'0124_H$	49_H
ASC1 Error	XP6IR	XP6IE	XP6INT	$00'0128_H$	$4A_H$
CAN2 (**C161CS**) or SDLM (**C161JC/JI**)	XP7IR	XP7IE	XP7INT	$00'012C_H$	$4B_H$

Serial Channels

Serial communication with other microcontrollers, processors, terminals or external peripheral components is provided by three serial interfaces with different functionality, two Asynchronous/Synchronous Serial Channels (**ASC0**/**ASC1**) and a High-Speed Synchronous Serial Channel (**SSC**).

The ASC0 is upward compatible with the serial ports of the Infineon 8-bit microcontroller families and supports full-duplex asynchronous communication at up to 781 kBaud and half-duplex synchronous communication at up to 3.1 MBaud (@ 25 MHz CPU clock).
A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling 4 separate interrupt vectors are provided. In asynchronous mode, 8- or 9-bit data frames are transmitted or received, preceded by a start bit and terminated by one or two stop bits. For multiprocessor communication, a mechanism to distinguish address from data bytes has been included (8-bit data plus wake up bit mode).
In synchronous mode, the ASC0 transmits or receives bytes (8 bits) synchronously to a shift clock which is generated by the ASC0. The ASC0 always shifts the LSB first. A loop back option is available for testing purposes.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. A parity bit can automatically be generated on transmission or be checked on reception. Framing error detection allows to recognize data frames with missing stop bits. An overrun error will be generated, if the last character received has not been read out of the receive buffer register at the time the reception of a new character is complete.

The ASC1 is function compatible with the ASC0, except that its registers are not bit-addressable (XBUS peripheral) and it provides only three interrupt vectors.

The SSC supports full-duplex synchronous communication at up to 6.25 MBaud (@ 25 MHz CPU clock). It may be configured so it interfaces with serially linked peripheral components. A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling three separate interrupt vectors are provided.
The SSC transmits or receives characters of 2 … 16 bits length synchronously to a shift clock which can be generated by the SSC (master mode) or by an external master (slave mode). The SSC can start shifting with the LSB or with the MSB and allows the selection of shifting and latching clock edges as well as the clock polarity.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. Transmit and receive error supervise the correct handling of the data buffer. Phase and baudrate error detect incorrect serial data.

Serial Data Link Module (SDLM)

The Serial Data Link Module (SDLM) provides serial communication via a J1850 type multiplexed serial bus via an external J1850 bus transceiver. The module conforms to the SAE Class B J1850 specification for variable pulse width modulation (VPW). The SDLM is integrated as an on-chip peripheral and is connected to the CPU via the XBUS.

General SDLM Features:

- Compliant to the SAE Class B J1850 specification (VPW)
- Class 2 protocol fully supported
- Variable Pulse Width (VPW) operation at 10.4 kBaud
- High Speed 4X operation at 41.6 kBaud
- Programmable Normalization Bit
- Programmable Delay for transceiver interface
- Digital Noise Filter
- Power Down mode with automatic wakeup support upon bus activity
- Single Byte Header and Consolidated Header supported
- CRC generation and checking
- Receive and transmit Block Mode

Data Link Operation Features:

- 11 Byte Transmit Buffer
- Double buffered 11 Byte receive buffer (optional overwrite enable)
- Support for In Frame Response (IFR) types 1, 2 and 3
- Transmit and Receiver Message Buffers configurable for either FIFO or Byte mode
- Advanced Interrupt Handling with 8 separately enabled sources:
  Error, format or bus shorted
  CRC error
  Lost Arbitration
  Break received
  In-Frame-Response request
  Header received
  Complete message received
  Transmit successful
- Automatic IFR transmission (Types 1 and 2) for 3-Byte consolidated headers
- User configurable clock divider
- Bus status flags (IDLE, EOF, EOD, SOF, Tx and Rx in progress)

Note: When the SDLM is used with the interface lines assigned to Port 4, the interface lines override the segment address lines and the segment address output on Port 4 is therefore limited to 6/4 bits i.e. address lines A21/A19 … A16. $\overline{CS}$ lines can be used to increase the total amount of addressable external memory.

CAN-Modules

The integrated CAN-Modules handle the completely autonomous transmission and reception of CAN frames in accordance with the CAN specification V2.0 part B (active), i.e. the on-chip CAN-Modules can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers.

The modules provide Full CAN functionality on up to 15 message objects each. Message object 15 may be configured for Basic CAN functionality. Both modes provide separate masks for acceptance filtering which allows to accept a number of identifiers in Full CAN mode and also allows to disregard a number of identifiers in Basic CAN mode. All message objects can be updated independent from the other objects and are equipped for the maximum message length of 8 bytes.

The bit timing is derived from the XCLK and is programmable up to a data rate of 1 MBaud. Each CAN-Module uses two pins of Port 4 or Port 8 to interface to an external bus transceiver. The interface pins are assigned via software.

Module CAN2 (C161CS only) is identical with the first one, except that it uses a separate address area and a separate interrupt node.

The two CAN modules can be internally coupled by assigning their interface pins to the same two port pins, or they can interface to separate CAN buses.

Note: When one or both of the on-chip CAN Modules are used with the interface lines assigned to Port 4, the interface lines override the segment address lines and the segment address output on Port 4 is therefore limited to 6/4 bits i.e. address lines A21/A19 … A16. $\overline{CS}$ lines can be used to increase the total amount of addressable external memory.

IIC Module

The integrated IIC Bus Module handles the transmission and reception of frames over the two-line IIC bus in accordance with the IIC Bus specification. The on-chip IIC Module can receive and transmit data using 7-bit or 10-bit addressing and it can operate in slave mode, in master mode or in multi-master mode.

Several physical interfaces (port pins) can be established under software control. Data can be transferred at speeds up to 400 kbit/sec.

Two interrupt nodes dedicated to the IIC module allow efficient interrupt service and also support operation via PEC transfers.

Note: The port pins associated with the IIC interfaces feature open drain drivers only, as required by the IIC specification.

Instruction Set Summary

Table 6 lists the instructions of the C161CS/JC/JI in a condensed way.
The various addressing modes that can be used with a specific instruction, the operation of the instructions, parameters for conditional execution of instructions, and the opcodes for each instruction can be found in the **“C166 Family Instruction Set Manual”**.

This document also provides a detailled description of each instruction.

Table 6 Instruction Set Summary

Mnemonic	Description	Bytes
ADD(B)	Add word (byte) operands	2 / 4
ADDC(B)	Add word (byte) operands with Carry	2 / 4
SUB(B)	Subtract word (byte) operands	2 / 4
SUBC(B)	Subtract word (byte) operands with Carry	2 / 4
MUL(U)	(Un)Signed multiply direct GPR by direct GPR (16-16-bit)	2
DIV(U)	(Un)Signed divide register MDL by direct GPR (16-/16-bit)	2
DIVL(U)	(Un)Signed long divide reg. MD by direct GPR (32-/16-bit)	2
CPL(B)	Complement direct word (byte) GPR	2
NEG(B)	Negate direct word (byte) GPR	2
AND(B)	Bitwise AND, (word/byte operands)	2 / 4
OR(B)	Bitwise OR, (word/byte operands)	2 / 4
XOR(B)	Bitwise XOR, (word/byte operands)	2 / 4
BCLR	Clear direct bit	2
BSET	Set direct bit	2
BMOV(N)	Move (negated) direct bit to direct bit	4
BAND, BOR, BXOR	AND/OR/XOR direct bit with direct bit	4
BCMP	Compare direct bit to direct bit	4
BFLDH/L	Bitwise modify masked high/low byte of bit-addressable direct word memory with immediate data	4
CMP(B)	Compare word (byte) operands	2 / 4
CMPD1/2	Compare word data to GPR and decrement GPR by 1/2	2 / 4
CMPI1/2	Compare word data to GPR and increment GPR by 1/2	2 / 4
PRIOR	Determine number of shift cycles to normalize direct word GPR and store result in direct word GPR	2
SHL / SHR	Shift left/right direct word GPR	2
ROL / ROR	Rotate left/right direct word GPR	2
ASHR	Arithmetic (sign bit) shift right direct word GPR	2

Table 6 Instruction Set Summary (cont'd)

Mnemonic	Description	Bytes
MOV(B)	Move word (byte) data	2 / 4
MOVBS	Move byte operand to word operand with sign extension	2 / 4
MOVBZ	Move byte operand to word operand. with zero extension	2 / 4
JMPA, JMPI, JMPR	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
J(N)B	Jump relative if direct bit is (not) set	4
JBC	Jump relative and clear bit if direct bit is set	4
JNBS	Jump relative and set bit if direct bit is not set	4
CALLA, CALLI, CALLR	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH, POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack and update register with word operand	4
RET	Return from intra-segment subroutine	2
RETS	Return from inter-segment subroutine	2
RETP	Return from intra-segment subroutine and pop direct word register from system stack	2
RETI	Return from interrupt service subroutine	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Enter Power Down Mode (supposes $\overline{\text{NMI}}$-pin being low)	4
SRVWDT	Service Watchdog Timer	4
DISWDT	Disable Watchdog Timer	4
EINIT	Signify End-of-Initialization on RSTOUT-pin	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTended Register sequence	2
EXTP(R)	Begin EXTended Page (and Register) sequence	2 / 4
EXTS(R)	Begin EXTended Segment (and Register) sequence	2 / 4
NOP	Null operation	2

Parameter Interpretation

The parameters listed in the following partly represent the characteristics of the C161CS/JC/JI and partly its demands on the system. To aid in interpreting the parameters right, when evaluating them for a design, they are marked in column “Symbol”:

CC (**C**ontroller **C**haracteristics):
The logic of the C161CS/JC/JI will provide signals with the respective timing characteristics.

SR (**S**ystem **R**equirement):
The external system must provide signals with the respective timing characteristics to the C161CS/JC/JI.

DC Characteristics

(Operating Conditions apply)[1)]

Parameter	Symbol		Limit Values		Unit	Test Condition
			min.	max.		
Input low voltage (TTL, all except XTAL1, XTAL3, Port 9)	V_{IL}	SR	-0.5	0.2 V_{DD} - 0.1	V	–
Input low voltage XTAL1, XTAL3, Port 9	V_{IL2}	SR	-0.5	0.3 V_{DD}	V	–
Input low voltage (Special Threshold)	V_{ILS}	SR	-0.5	2.0	V	–
Input high voltage (TTL, all except $\overline{\text{RSTIN}}$, XTAL1, XTAL3, Port 9)	V_{IH}	SR	0.2 V_{DD} + 0.9	V_{DD} + 0.5	V	–
Input high voltage $\overline{\text{RSTIN}}$ (when operated as input)	V_{IH1}	SR	0.6 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage XTAL1, XTAL3, Port 9	V_{IH2}	SR	0.7 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage (Special Threshold)	V_{IHS}	SR	0.8 V_{DD} - 0.2	V_{DD} + 0.5	V	–
Input Hysteresis (Special Threshold)	HYS		400	–	mV	Series resistance = 0 Ω
Output low voltage (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$, $\overline{\text{RSTIN}}$[2)])	V_{OL}	CC	–	0.45	V	I_{OL} = 2.4 mA[3)] I_{OL} = 0.5 mA[4)]
Output low voltage (Port 9)	V_{OL9}	CC	–	0.4	V	I_{OL} = 3.0 mA

6) These parameters describe the $\overline{\text{RSTIN}}$ pullup, which equals a resistance of ca. 50 to 250 kΩ.

7) The maximum current may be drawn while the respective signal line remains inactive.

8) The minimum current must be drawn in order to drive the respective signal line active.

9) This specification is valid during Reset and during Hold-mode or Adapt-mode. During Hold-mode Port 6 pins are only affected, if they are used (configured) for $\overline{\text{CS}}$ output and the open drain function is not enabled. The $\overline{\text{READY}}$-pullup is always active, except for Powerdown mode.

10) This specification is valid during Reset and during Adapt-mode.

11) Not 100% tested, guaranteed by design and characterization.

Power Consumption C161CS/JC/JI

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Power supply current (active) with all peripherals active	I_{DD}	–	15 + 2.5 × f_{CPU}	mA	$\overline{\text{RSTIN}}$ = V_{IL} f_{CPU} in [MHz][1]
Idle mode supply current with all peripherals active	I_{IDX}	–	5 + 1.5 × f_{CPU}	mA	$\overline{\text{RSTIN}}$ = V_{IH1} f_{CPU} in [MHz][1]
Idle mode supply curr., Main osc, with all peripherals deactivated, PLL off, SDD factor = 32	I_{IDOM}[2]	–	500 + 50 × f_{OSC}	µA	$\overline{\text{RSTIN}}$ = V_{IH1} f_{OSC} in [MHz][1]
Idle mode supply curr., Aux. osc, with all peripherals deactivated, PLL off, SDD factor = 32	I_{IDOA}[2]	–	100	µA	V_{DD} = V_{DDmax} f_{OSC} = 32 kHz[3]
Sleep and Power-down mode supply current with RTC running on main oscillator	I_{PDRM}[2]	–	200 + 25 × f_{OSC}	µA	V_{DD} = V_{DDmax} f_{OSC} in [MHz][3]
Sleep and Power-down mode supply current with RTC disabled	I_{PDO}	–	50	µA	V_{DD} = V_{DDmax}[3]

1) The supply current is a function of the operating frequency. This dependency is illustrated in **Figure 10**. These parameters are tested at V_{DDmax} and maximum CPU clock with all outputs disconnected and all inputs at V_{IL} or V_{IH}.

2) This parameter is determined mainly by the current consumed by the oscillator (see **Figure 9**). This current, however, is influenced by the external oscillator circuitry (crystal, capacitors). The values given refer to a typical circuitry and may change in case of a not optimized external oscillator circuitry.

3) This parameter is tested including leakage currents. All inputs (including pins configured as inputs) at 0 V to 0.1 V or at V_{DD} - 0.1 V to V_{DD}, all outputs (including pins configured as outputs) disconnected.

A/D Converter Characteristics

(Operating Conditions apply)

Table 13 A/D Converter Characteristics

Parameter	Symbol		Limit Values		Unit	Test Condition
			min.	max.		
Analog reference supply	V_{AREF}	SR	4.0	V_{DD} + 0.1	V	1)
Analog reference ground	V_{AGND}	SR	V_{SS} - 0.1	V_{SS} + 0.2	V	
Analog input voltage range	V_{AIN}	SR	V_{AGND}	V_{AREF}	V	2)
Basic clock frequency	f_{BC}		0.5	6.25	MHz	3)
Conversion time	t_C	CC	–	40 t_{BC} + t_S + 2t_{CPU}	–	4) $t_{CPU} = 1 / f_{CPU}$
Calibration time after reset	t_{CAL}	CC	–	3328 t_{BC}	–	5)
Total unadjusted error	TUE	CC	–	±2	LSB	1)
Internal resistance of reference voltage source	R_{AREF}	SR	–	t_{BC} / 60 - 0.25	kΩ	t_{BC} in [ns]6)7)
Internal resistance of analog source	R_{ASRC}	SR	–	t_S / 450 - 0.25	kΩ	t_S in [ns]7)8)
ADC input capacitance	C_{AIN}	CC	–	33	pF	7)

1) TUE is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V, V_{DD} = 4.9 V. It is guaranteed by design for all other voltages within the defined voltage range.
If the analog reference supply voltage exceeds the power supply voltage by up to 0.2 V (i.e. V_{AREF} = V_{DD} = +0.2 V) the maximum TUE is increased to ±3 LSB. This range is not 100% tested.
The specified TUE is guaranteed only if the absolute sum of input overload currents on Port 5 pins (see I_{OV} specification) does not exceed 10 mA.
During the reset calibration sequence the maximum TUE may be ±4 LSB.

2) V_{AIN} may exceed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be $X000_H$ or $X3FF_H$, respectively.

3) The limit values for f_{BC} must not be exceeded when selecting the CPU frequency and the ADCTC setting.

4) This parameter includes the sample time t_S, the time for determining the digital result and the time to load the result register with the conversion result.
Values for the basic clock t_{BC} depend on programming and can be taken from **Table 14**.
This parameter depends on the ADC control logic. It is not a real maximum value, but rather a fixum.

5) During the reset calibration conversions can be executed (with the current accuracy). The time required for these conversions is added to the total reset calibration time.

6) During the conversion the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference voltage source must allow the capacitance to reach its respective voltage level within each conversion step. The maximum internal resistance results from the programmed conversion timing.

7) Not 100% tested, guaranteed by design and characterization.

Multiplexed Bus (cont'd)
(Operating Conditions apply)
ALE cycle time = 6 TCL + $2t_A$ + t_C + t_F (120 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
$\overline{RD}$, $\overline{WR}$ low time (no RW-delay)	t_{13}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns
$\overline{RD}$ to valid data in (with RW-delay)	t_{14}	SR	–	20 + t_C	–	2TCL - 20 + t_C	ns
$\overline{RD}$ to valid data in (no RW-delay)	t_{15}	SR	–	40 + t_C	–	3TCL - 20 + t_C	ns
ALE low to valid data in	t_{16}	SR	–	40 + t_A + t_C	–	3TCL - 20 + t_A + t_C	ns
Address to valid data in	t_{17}	SR	–	50 + $2t_A$ + t_C	–	4TCL - 30 + $2t_A$ + t_C	ns
Data hold after $\overline{RD}$ rising edge	t_{18}	SR	0	–	0	–	ns
Data float after $\overline{RD}$	t_{19}	SR	–	26 + t_F	–	2TCL - 14 + t_F	ns
Data valid to $\overline{WR}$	t_{22}	CC	20 + t_C	–	2TCL - 20 + t_C	–	ns
Data hold after $\overline{WR}$	t_{23}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
ALE rising edge after $\overline{RD}$, $\overline{WR}$	t_{25}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
Address hold after $\overline{RD}$, $\overline{WR}$	t_{27}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
ALE falling edge to $\overline{CS}$[1)]	t_{38}	CC	-4 - t_A	10 - t_A	-4 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In[1)]	t_{39}	SR	–	40 + t_C + $2t_A$	–	3TCL - 20 + t_C + $2t_A$	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$[1)]	t_{40}	CC	46 + t_F	–	3TCL - 14 + t_F	–	ns
ALE fall. edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW delay)	t_{42}	CC	16 + t_A	–	TCL - 4 + t_A	–	ns

AC Characteristics

Demultiplexed Bus

(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
ALE high time	t_5	CC	10 + t_A	–	TCL - 10 + t_A	–	ns
Address setup to ALE	t_6	CC	4 + t_A	–	TCL - 16 + t_A	–	ns
ALE falling edge to $\overline{RD}$, $\overline{WR}$ (with RW-delay)	t_8	CC	10 + t_A	–	TCL - 10 + t_A	–	ns
ALE falling edge to $\overline{RD}$, $\overline{WR}$ (no RW-delay)	t_9	CC	-10 + t_A	–	-10 + t_A	–	ns
$\overline{RD}$, $\overline{WR}$ low time (with RW-delay)	t_{12}	CC	30 + t_C	–	2TCL - 10 + t_C	–	ns
$\overline{RD}$, $\overline{WR}$ low time (no RW-delay)	t_{13}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns
$\overline{RD}$ to valid data in (with RW-delay)	t_{14}	SR	–	20 + t_C	–	2TCL - 20 + t_C	ns
$\overline{RD}$ to valid data in (no RW-delay)	t_{15}	SR	–	40 + t_C	–	3TCL - 20 + t_C	ns
ALE low to valid data in	t_{16}	SR	–	40 + t_A + t_C	–	3TCL - 20 + t_A + t_C	ns
Address to valid data in	t_{17}	SR	–	50 + 2t_A + t_C	–	4TCL - 30 + 2t_A + t_C	ns
Data hold after $\overline{RD}$ rising edge	t_{18}	SR	0	–	0	–	ns
Data float after $\overline{RD}$ rising edge (with RW-delay[1)])	t_{20}	SR	–	26 + 2t_A + t_F[1)]	–	2TCL - 14 + 22t_A + t_F[1)]	ns
Data float after $\overline{RD}$ rising edge (no RW-delay[1)])	t_{21}	SR	–	10 + 2t_A + t_F[1)]	–	TCL - 10 + 22t_A + t_F[1)]	ns

Demultiplexed Bus (cont'd)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
Data float after $\overline{\text{RdCS}}$ (no RW-delay)[1]	t_{68}	SR	–	0 + t_F	–	TCL - 20 + 2t_A + t_F[1]	ns
Address hold after $\overline{\text{RdCS}}$, $\overline{\text{WrCS}}$	t_{55}	CC	-6 + t_F	–	-6 + t_F	–	ns
Data hold after $\overline{\text{WrCS}}$	t_{57}	CC	6 + t_F	–	TCL - 14 + t_F	–	ns

1) RW-delay and t_A refer to the next following bus cycle (including an access to an on-chip X-Peripheral).

2) Read data are latched with the same clock edge that triggers the address change and the rising $\overline{\text{RD}}$ edge. Therefore address changes before the end of $\overline{\text{RD}}$ have no impact on read cycles.

3) These parameters refer to the latched chip select signals ($\overline{\text{CSxL}}$). The early chip select signals ($\overline{\text{CSxE}}$) are specified together with the address and signal $\overline{\text{BHE}}$ (see figures below).

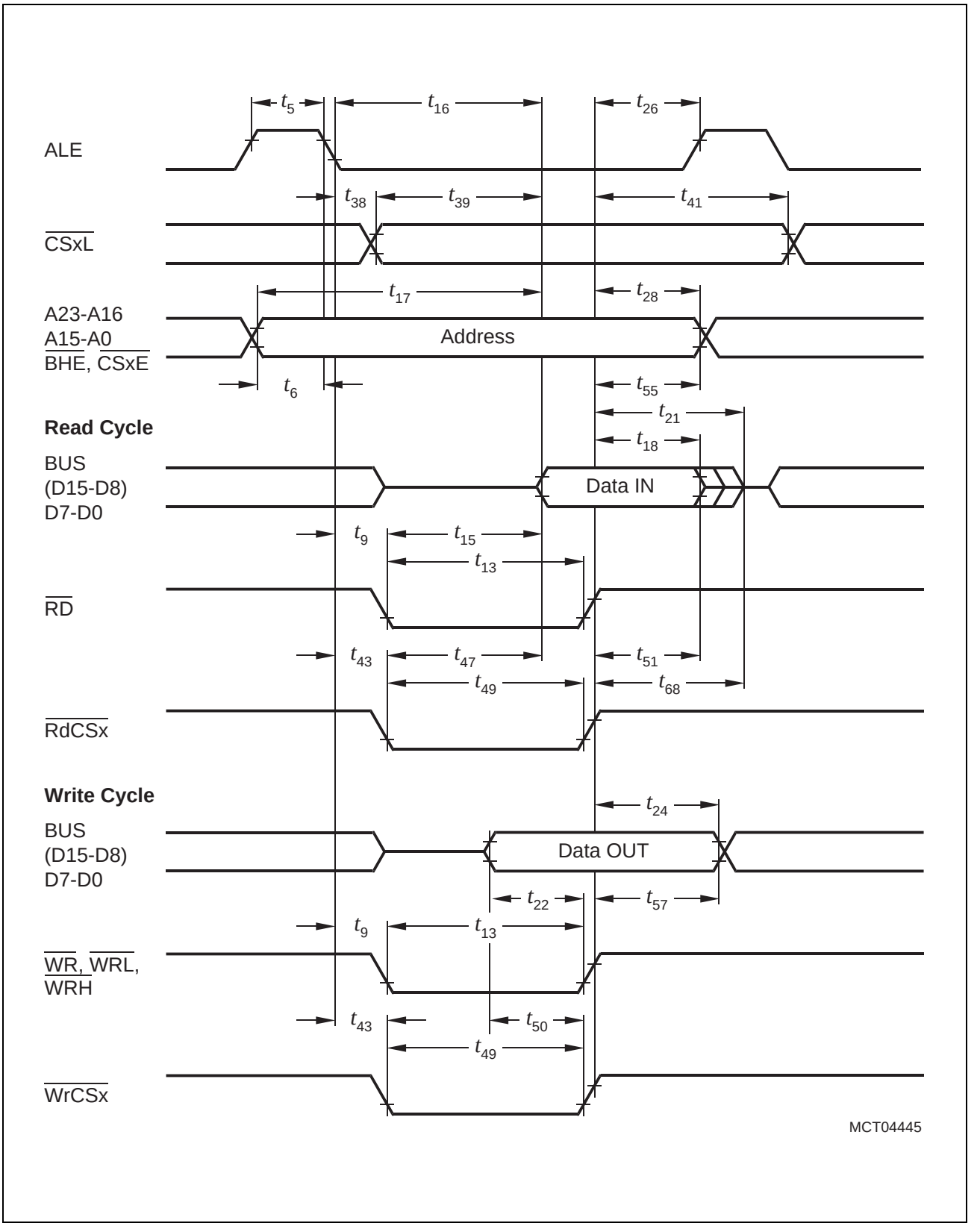


**Figure 22 External Memory Cycle:
Demultiplexed Bus, No Read/Write Delay, Normal ALE**

AC Characteristics

External Bus Arbitration

(Operating Conditions apply)

Parameter	Symbol	Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
		min.	max.	min.	max.	
$\overline{\text{HOLD}}$ input setup time to CLKOUT	t_{61} SR	20	–	20	–	ns
CLKOUT to $\overline{\text{HLDA}}$ high or $\overline{\text{BREQ}}$ low delay	t_{62} CC	–	20	–	20	ns
CLKOUT to $\overline{\text{HLDA}}$ low or $\overline{\text{BREQ}}$ high delay	t_{63} CC	–	20	–	20	ns
$\overline{\text{CSx}}$ release	t_{64} CC	–	20	–	20	ns
$\overline{\text{CSx}}$ drive	t_{65} CC	-4	24	-4	24	ns
Other signals release	t_{66} CC	–	20	–	20	ns
Other signals drive	t_{67} CC	– 4	24	– 4	24	ns

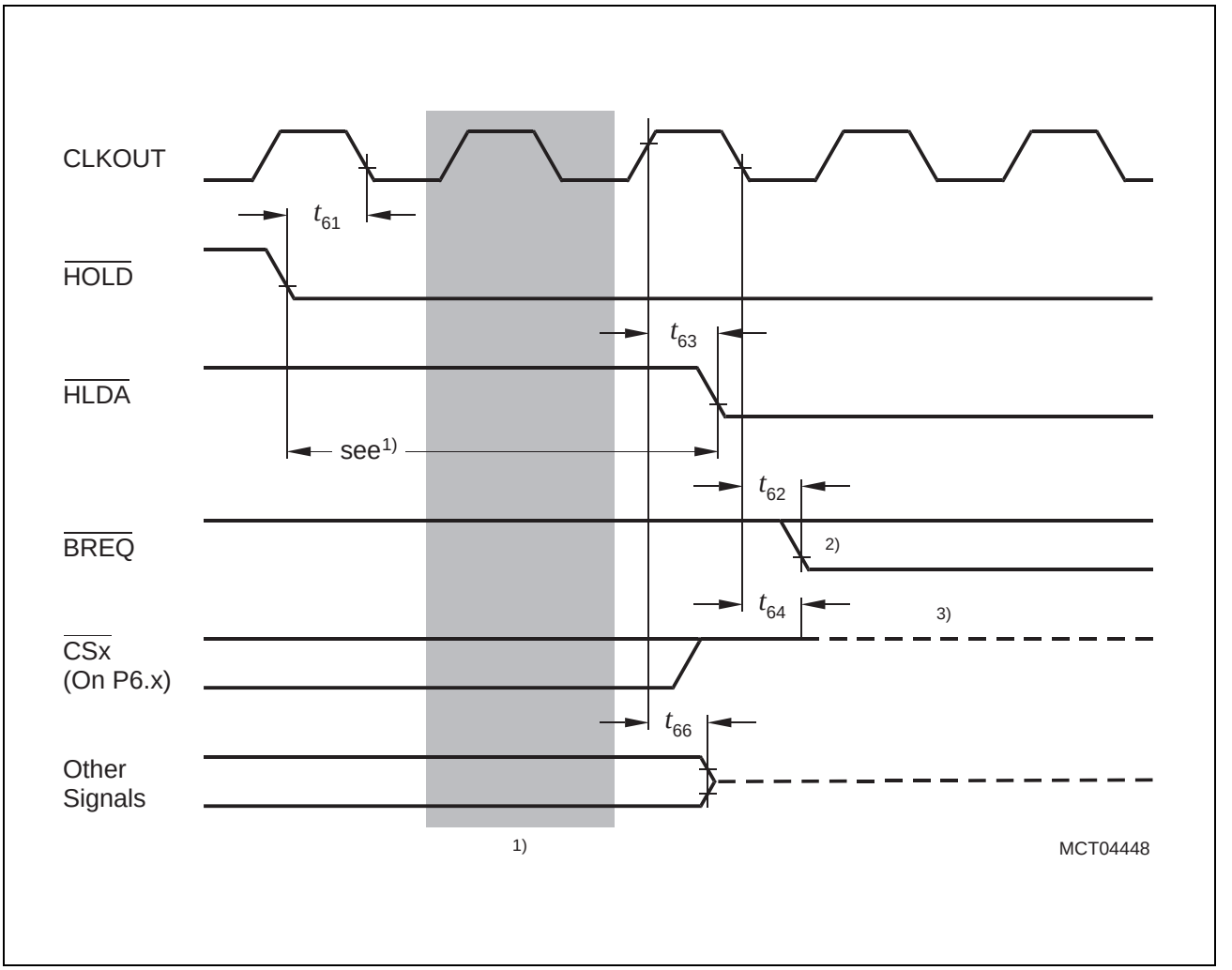
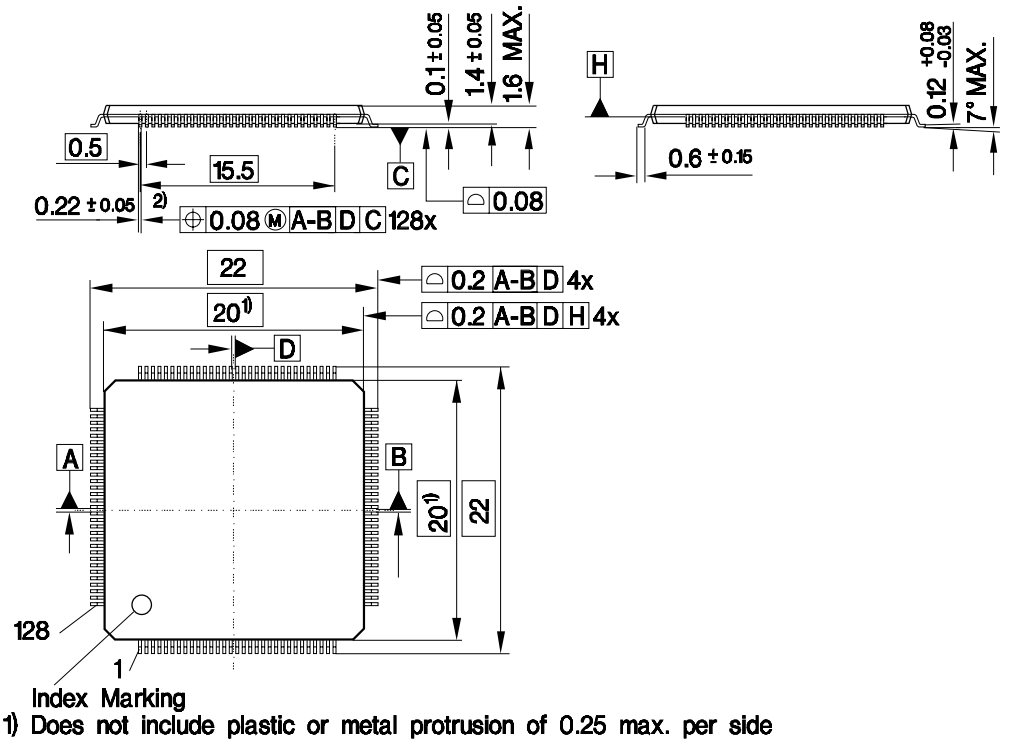


Figure 25 External Bus Arbitration, Releasing the Bus

Notes
1) The C161CS/JC/JI will complete the currently running bus cycle before granting bus access.
2) This is the first possibility for $\overline{\text{BREQ}}$ to get active.
3) The $\overline{\text{CS}}$ outputs will be resistive high (pullup) after t_{64}.

Package Outline

P-TQFP-128-2
(Plastic Thin Metric Quad Flat Package)



GPP09028

Sorts of Packing
Package outlines for tubes, trays etc. are contained in our Data Book “Package Information”.

SMD = Surface Mounted Device

Dimensions in mm